



**产品编号: NY6600**

**特点:**

- 低介电常数(Dk 3.95@10GHz)
- 介质损耗(Df 0.0045@10GHz)
- Tg >200°C 高耐热性
- 优异通孔可靠性及 PCB 加工性

**FEATURES:**

- Low Dk (Dk 3.95@10GHz)
- Low Df (Df 0.0045@10GHz)
- Tg >200°C and high thermostability
- Superior PTH reliability and easy PCB processing

**NY6600 基板产品规格表 Specification Sheet for Laminate**

NY6600 覆铜板 NY6600 Laminate	单位Units	典型值 Typical Value	条件 Condition	测试方法 Test Method
	Metric(English)	1.524mm CCL		IPC-TM-650
1. 玻璃态转化温度 Glass Transition Temperature	°C	250	DMA	2.4.24.4
	°C	210	TMA	2.4.24
2. 膨胀系数Z-Axis CTE A. 50 to 260 °C	%	1.95	TMA	2.4.24
3. 膨胀系数X/Y CTE A. 50 to 125°C	ppm/°C	20/21	TMA	2.4.24
4. 热分解温度 Decomposition Temperature	°C	420		TD (5% wt loss)
5. 耐热性(除去铜箔) Thermal Resistance (Copper removed) A.T288 B.T300	Minutes Minutes	> 60 > 60	TMA	2.4.24.1
6. 介电常数 Permittivity (Laminate & Prepreg as laminated)	Maximum	3.95	10 GHz/23°C	SPDR
7. 介质损耗 Loss Tangent (Laminate & Prepreg as laminated)	Maximum	0.0045	10 GHz/23°C	SPDR
8. 吸水率 Moisture Absorption	% maximum	0.13		2.6.2.1
9. 抗剥强度 Peel Strength, As received	N/mm(lb/inch)	>0.9 (5.0)	1oz HVLP	2.4.8
10. 体积电阻 Volume Resistivity,	MΩ-cm, Minimum	> 10×10 <sup>10</sup>		2.5.17.1
11. 表面电阻 Surface Resistivity,	MΩ, minimum	> 10×10 <sup>9</sup>		2.5.17.1
12. 抗拉强度 Tensile strength	MPa	210/210 (径/纬)		GB/T 1040.1-2018
13. 弯曲强度 Flexural strength	MPa	400/425 (径/纬)		2.4.4.1B
14. 拉伸模量 Tensile Modulus	GPa	18/18 (径/纬)		GB/T 1040.1-2018
15. 泊松比 Poisson's Ratio	μb	0.2/0.2 (径/纬)		GB/T 1040.1-2018
16. 燃烧性 Flammability (Laminate & Prepreg as laminated)	Rating	V-0		UL94

\*AABUS = 供需双方商定 As agreed upon between user and supplier.